Special Issue

Piezoelectric MEMS/NEMS—Materials, Devices, and Applications, Third Edition

Message from the Guest Editor

Piezoelectric materials have been playing a crucial role in a large number of devices and applications that have promoted a variety of today's technological progress and impacted modern society. They are widely used as sensors and actuators, and they can be deposited as thin films over standard silicon substrates or flexible substrates. The appeal of piezoelectric materials for MEMS/NEMS has been constantly growing, in particular, with the increasing commercial success of piezoelectric MEMS/NEMS devices. The upcoming era of Big Data, sensors, the Internet of Things (IoT), and Artificial Intelligence (AI) has been offering new opportunities and challenges to piezoelectric MEMS/NEMS devices, and we are seeing researchers throughout the world actively tapping into the state-of-the-art micro/nano-fabrication process, promoting advanced integration techniques, and exploring innovative applications to unleash the potential of piezoelectric MEMS/NEMS devices. In this Special Issue, we invite submissions exploring the latest advances in the field of piezoelectric MEMS/NEMS devices.

Guest Editor

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